

# Material Declaration Report



Part Number:	PI2EQX3232BZDE
Package Type:	TQFN 48L
Pericom Package Code:	ZD48 (Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A
Date of RoHS Compliant:	Apr 1, 2007*

Component Weight (mg):	130.140
Termination Plating:	NIPdAu
JESD 97 Pb-free Category:	e4
Plating Thickness (um):	0.5-2.2
Tin Whisker Mitigation:	N/A

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	40
Reflow Cycles:	3
Date:	3/4/2008

## Homogeneous Material Declaration

ITEM	MATERIAL WEIGHT(mg)	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	45.390	Silica Fused	60676-86-0	90.800	41.2141
		Epoxy Resin 1	Proprietary	3.000	1.3617
		Epoxy Resin 2	Proprietary	2.000	0.9078
		Phenolic Resin	Proprietary	3.000	1.3617
		Aromatic Phosphate	Proprietary	1.000	0.4539
		Carbon Black	1333-86-4	0.200	0.0908
LEADFRAME	79.026	Copper (Cu)	7440-50-8	97.440	77.0029
		Iron (Fe)	7439-89-6	2.350	1.8571
		Phosphorus (P)	7723-14-0	0.080	0.0632
		Zinc (Zn)	7440-66-6	0.130	0.1027
SILICON DIE	2.910	Silicon (Si)	7440-21-3	99.192	2.8865
		Non-hazardous Metal	Proprietary	0.808	0.0235
DIE ATTACH EPOXY	0.250	Silver	7440-22-4	80.000	0.2000
		Bismaleimide	Proprietary	10.000	0.0250
		Polymer	Proprietary	7.000	0.0175
		Methacrylate Ester	Proprietary	3.000	0.0075
GOLD WIRE	2.150	Gold(Au)	7440-57-159	99.990	2.1498
		Impurities	-	0.010	0.0002
SOLDER PLATING	0.414	Nickel(Ni)	7440-02-0	93.000	0.3850
		Palladium(Pd)	2023-56-8	6.000	0.0248
		Gold(Au)	7440-57-5	1.000	0.0041

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

## 3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Leadframe	<19	<2	<2	<2	<5	<5
Device Silicon Die	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Plating	<2	<2	<2	<2	<5	<5

## ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC  and  China RoHS Directive SJ/T11363-2006	<b>Declaration Statement:</b>	Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium					
		Pb	Hg	Cr+6	Cd	PBB	PBDE
	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm	
	O	O	O	O	O	O	

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.  
X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.